Electronic Patent Application Fee Transmittal							
Application Number:	10	10739418					
Filing Date:	18-Dec-2003						
Title of Invention:	Flexible package with rigid substrate segments for high density integrated circuit systems						
First Named Inventor:	G	Gregory E. Howard					
Filer:	Yi	Yingsheng Tung/Jackie McBride					
Attorney Docket Number:	TI-35903						
Filed as Large Entity							
Utility Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							
Extension - 1 month with \$0 paid		1251	1	120	120		

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			120